

# PROGRAMME

## GRAPHENE CONNECT

### ELECTRONICS AND FLEXIBLE ELECTRONICS

GRAPHENE

CONNECT 

28 May 2019, Infineon, Regensburg, Germany

#### 27 May

19:00

**Kick off dinner at Leerer Beutel**Bertoldstraße 9, 93047 Regensburg, Germany (<https://leerer-beutel.de/>)

#### 28 May

9:00-9:15

**Registration**

9:15-9:30

**Welcome**

9:30-9:45

**Kari Hjelt – Head of Innovation, Graphene Flagship**

Graphene Flagship – Innovation and Success Stories

9:45-10:15

**Keynote speaker: Stephan Pindl – Infineon**

2D or not 2D – Graphene as high potential in manifold semiconductor applications

10:15-10:45

**Coffee Break**

#### Parallel sessions

10:45-12:05

#### ELECTRONICS

**Cedric Huyghebaert – IMEC**

2D materials: roadmap to integration with CMOS platforms

**Daniel Neumaier – AMO**Graphene based electronic devices:  
Current status, challenges and possible applications**Iñigo Charola – Graphenea**

Graphene Foundry Services to enable industry adoption

**Tapani Ryhänen – Emberion**

Graphene enhanced infrared imaging

#### FLEXIBLE ELECTRONICS

**Andreas Roepert – Interactive wear AG**

From Hype 2.0 to Industry 4.0

**Emre-Ozan Polat – ICFO**Flexible Graphene Photodetectors for  
Wearable Fitness Monitoring**Miguel Vilaplana – Graphenicalab**

Challenges printing flexible electronics and sensors

**Chris Jones – Novalia Ltd**

Flexible Electronics &amp; the Consumer Experience

12:05-13:20 **Lunch**13:20-14:20 **Group discussion**

Future trends and relevant applications

**Group discussion**

Future trends and relevant applications

14:20-14:30 **Summary, Way forward**14:30-16:00 **Visit Production line**

16:00

**End and departure**